

**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** [503821-5281](#)  
**Status:** **Active**  
**Description:** Array-Beam™ Plug, 528 Circuits, 4.00mm Mated Height, SMT, 12 Rows, Without Pegs

**Documents:**

[Drawing \(PDF\)](#) [Packaging Specification SPK-503821-001 \(PDF\)](#)  
[Product Specification PS-503825-001 \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)  
[Application Specification AS-503825-001 \(PDF\)](#)

**General**

Product Family	PCB Headers
Series	503821
Application	Board-to-Board
Product Name	Array-Beam™
UPC	887191055657

**Physical**

Breakaway	No
Circuits (Loaded)	528
Circuits (maximum)	528
Color - Resin	Black
Durability (mating cycles max)	50
First Mate / Last Break	No
Glow-Wire Compliant	No
Mated Height	4.00mm
Material - Metal	Copper
Material - Plating Mating	Gold
Net Weight	2954.620/mg
Number of Rows	12
Orientation	Vertical
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface	1.27mm
Pitch - Termination Interface	1.27mm
Temperature Range - Operating	-55°C to +85°C
Termination Interface: Style	Surface Mount

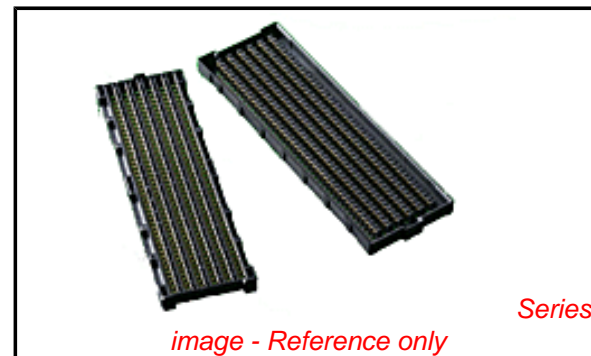
**Electrical**

Current - Maximum per Contact	2A
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**Material Info**

**Reference - Drawing Numbers**

Application Specification	AS-503825-001
Packaging Specification	SPK-503821-001
Product Specification	PS-503825-001
Sales Drawing	SD-503821-002, SD-503821-003



**EU RoHS**

**ELV and RoHS  
Compliant**  
**REACH SVHC  
Contains SVHC: No  
Low-Halogen Status  
Low-Halogen**

**China RoHS**



**Need more information on product  
environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**

503821Series

**Mates With**

Array-Beam™ Receptacle [503825](#)

**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** [503825-5281](#)  
**Status:** **Active**  
**Description:** Array-Beam™ Receptacle, 528 Circuits, 4.00mm Mated Height, SMT, 12 Rows, Without Pegs

**Documents:**

[Drawing \(PDF\)](#) [Packaging Specification SPK-503825-001 \(PDF\)](#)  
[Product Specification PS-503825-001 \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)  
[Application Specification AS-503825-001 \(PDF\)](#)

**General**

Product Family	PCB Receptacles
Series	<a href="#">503825</a>
Application	Board-to-Board
Product Name	Array-Beam™
UPC	887191055473

**Physical**

Circuits (Loaded)	528
Circuits (maximum)	528
Color - Resin	Black
Durability (mating cycles max)	50
Glow-Wire Compliant	No
Mated Height	4.00mm
Material - Metal	Copper
Material - Plating Mating	Gold
Net Weight	3324.560/mg
Number of Rows	12
Orientation	Vertical
PCB Retention	None
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface	1.27mm
Pitch - Termination Interface	1.27mm
Polarized to PCB	Yes
Temperature Range - Operating	-55°C to +85°C
Termination Interface: Style	Surface Mount

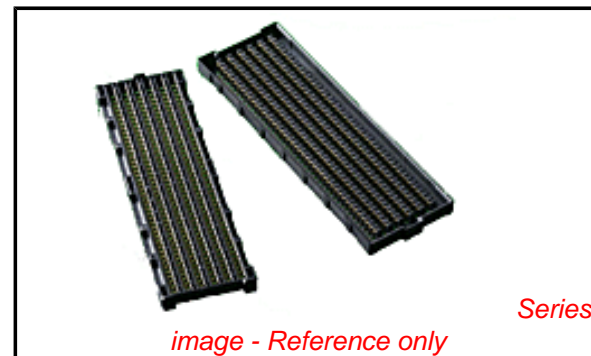
**Electrical**

Current - Maximum per Contact	2A
Voltage - Maximum	200V

**Material Info**

**Reference - Drawing Numbers**

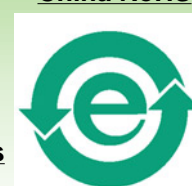
Application Specification	AS-503825-001
Packaging Specification	SPK-503825-001
Product Specification	PS-503825-001
Sales Drawing	SD-503825-002, SD-503825-003



**EU RoHS**

**ELV and RoHS Compliant**  
**REACH SVHC**  
**Contains SVHC: No**  
**Low-Halogen Status**  
**Low-Halogen**

**China RoHS**



**Need more information on product environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

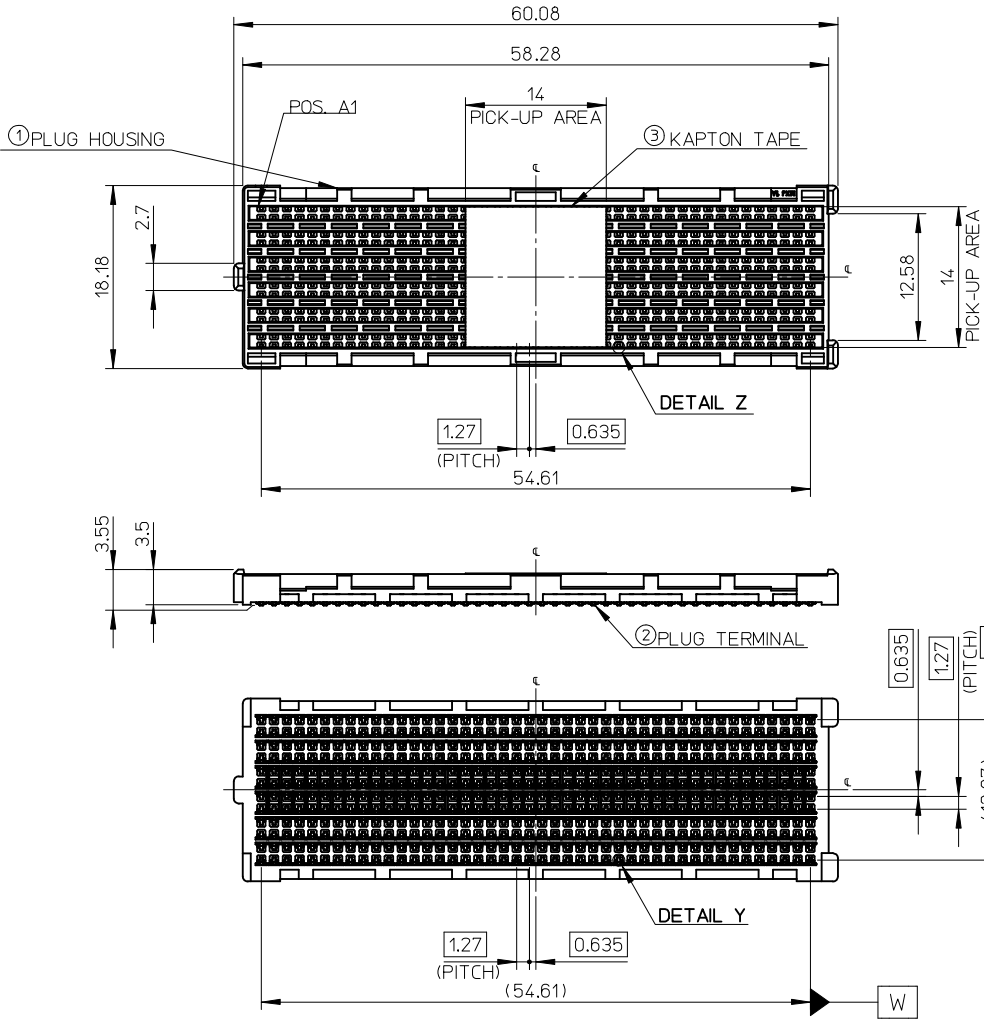
**Search Parts in this Series**

[503825Series](#)

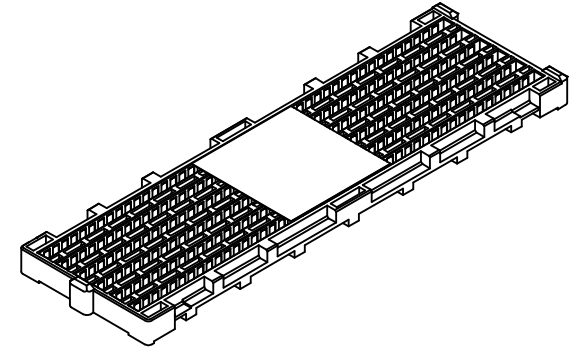
**Mates With**

Array-Beam™ Plug [503821](#)

10 9 8 7 6 5 4 3 2 1

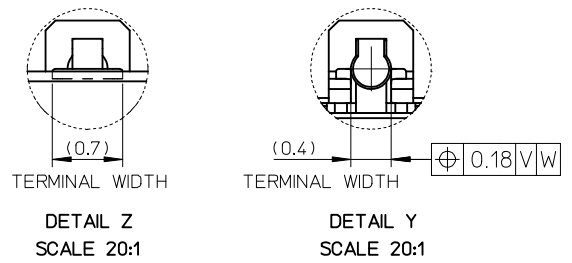


番号 No.	部品 PART	材質 MATERIAL
①	プラグ ハウジング PLUG HOUSING	液晶ポリマー、UL94V-0、黒色 LIQUID CRYSTAL POLYMER (LCP), UL94V-0, COLOR:BLACK
②	プラグ ターミナル PLUG TERMINAL	銅合金 COPPER ALLOY
③	カプトンテープ KAPTON TAPE	ポリイミド POLYIMIDE



- NOTES
- メッキ仕様 PLATING  
金メッキ  
GOLD  
下地メッキ : ニッケルメッキ  
UNDER PLATING : NICKEL
  - 適合レセプタクル : 5038255281  
APPLICABLE RECEPTACLE : 5038255281
  - テール平坦度は0.15以下  
TAIL COPLANARITY TO BE 0.15 MAXIMUM.
  - ELV and RoHS COMPLIANT

5038215281	503821****
EMBOSSED PACKAGE	MODEL No.
ORDER No. オーダー番号	



RELEASED EC NO: J2013-1305 DRAWN: MNISHIKAWA 2013/05/14 CHECKED BY: CHIKIKAWANO 2013/05/14 APPR: MYAGI 2013/05/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3	ANGULAR ±1° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY MNISHIKAWA	DATE 2012/10/02	CHECKED BY KCHIKAWANO	DATE 2012/10/02	TITLE 1.27MM PITCH B-TO-B CONN HGT=4.0 528PIN PLUG ASSEMBLY	
	APPROVED BY MYAGI		DATE 2012/10/02	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-503821-002	SHEET NO. 1 OF 2	
	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2

10 9 8 7 6 5 4 3 2 1

F

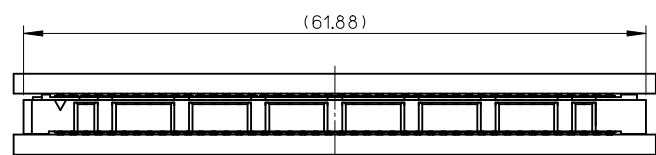
E

D

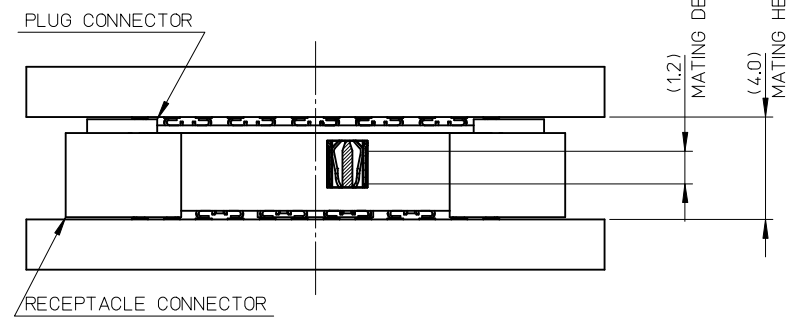
C

B

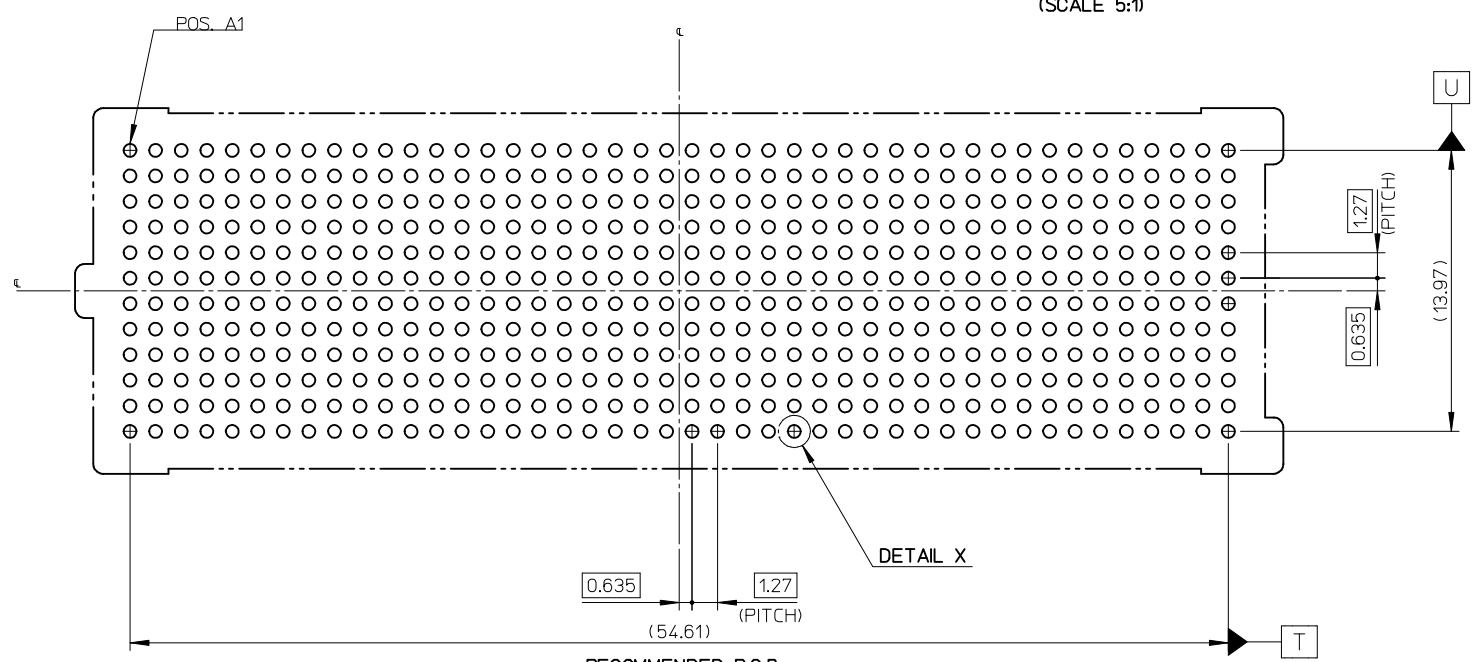
A



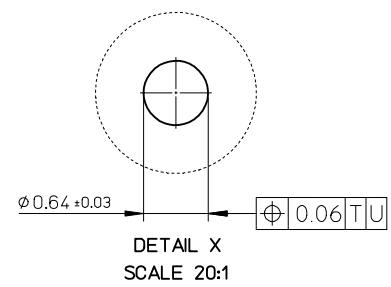
MATING CONNECTOR VIEW  
(SCALE 2:1)



(SCALE 5:1)



RECOMMENDED P.C.B.  
PATTERN LAYOUT



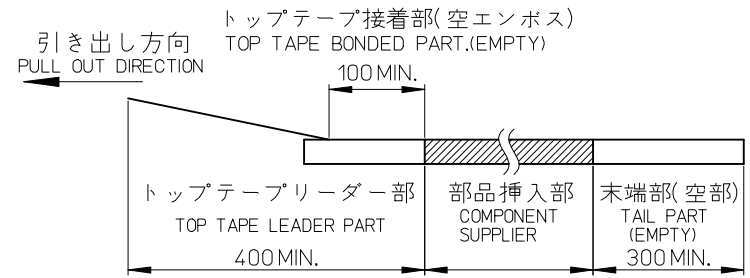
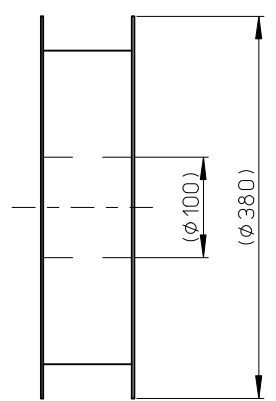
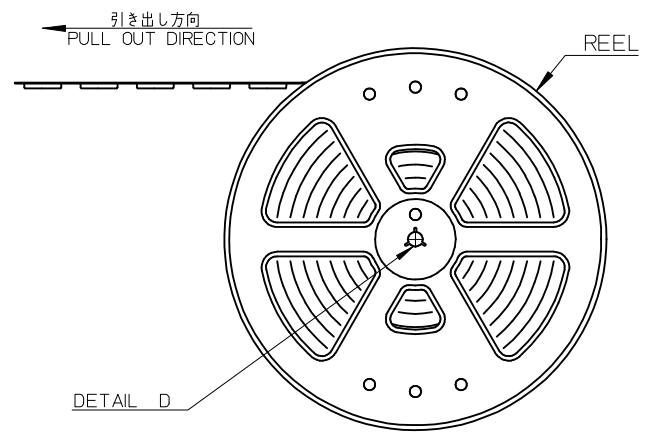
DETAIL X  
SCALE 20:1

RELEASED EC NO: J2013-1305 DRWN: MNISHIKAWA 2013/05/14 CHKD: KCHIKANO 2013/05/14 APPR: MYAGI 2013/05/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	$\pm 0.2$	DRAWN BY MNISHIKAWA	DATE 2012/10/02	TITLE 1.27MM PITCH B-TO-B CONN HGT=4.0 528PIN PLUG ASSEMBLY	
	10 OVER 30 UNDER	$\pm 0.25$	CHECKED BY KCHIKANO	DATE 2012/10/02		
	30 OVER	$\pm 0.3$	APPROVED BY MYAGI	DATE 2012/10/02	<b>molex</b> DOCUMENT NO. SD-503821-002 SHEET NO. 2 OF 2	
	ANGULAR $\pm 1^\circ$		MATERIAL NO. SEE SHEET 1			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

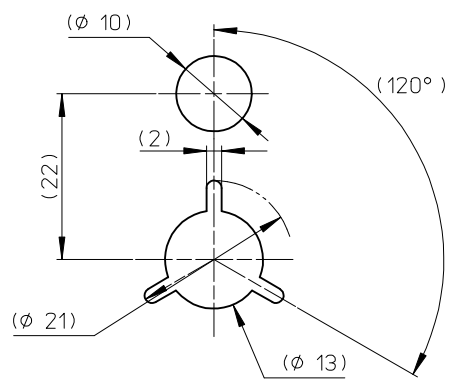
9 8 7 6 5 4 3 2

NOTES

- 製品詳細寸法については、SD図面を参照下さい。  
THE DETAIL DIMENSION REFER TO SALES DRAWING.
- 梱包数量：500 個／リール  
NUMBER OF CONNECTORS : 500 PCS/REEL.
- リードテープ長さ LEAD TAPE LENGTH.

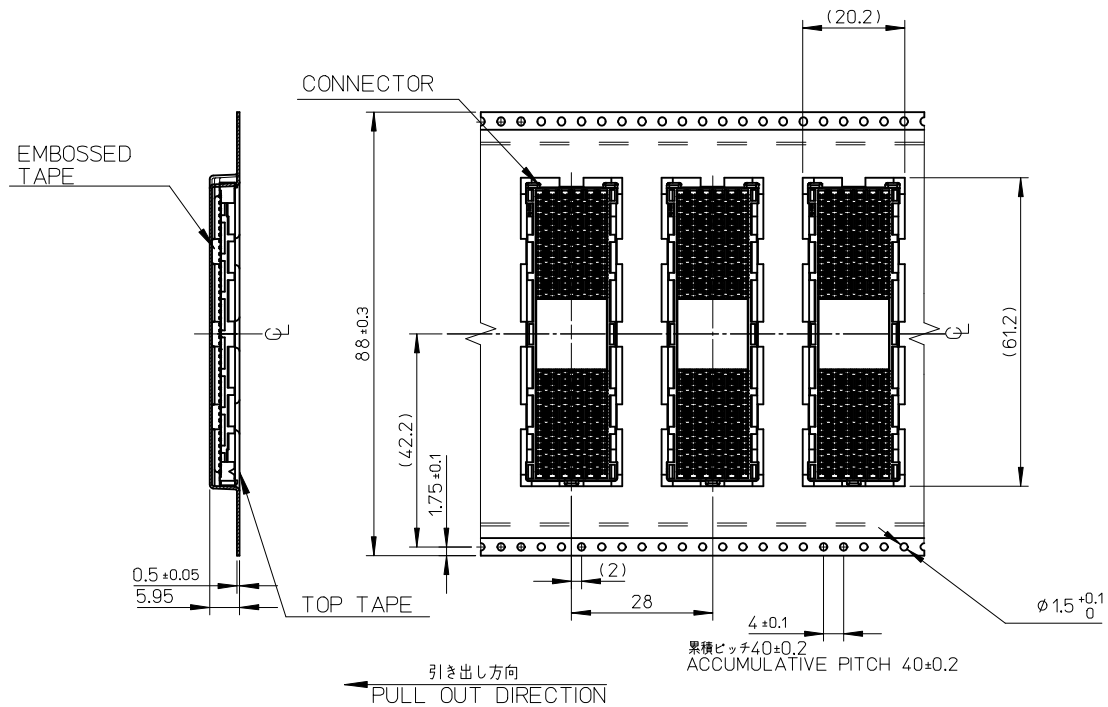


- トップテープの剥離強度については、IEC60286-3に準拠  
TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.
- 材料 MATERIAL  
キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)  
トップテープ (TOP TAPE) : PET, OTHER  
リール (REEL) : ポリスチレン (PS) <リサイクル材含む>  
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- ELV 及び RoHS適合品  
ELV AND RoHS COMPLIANT



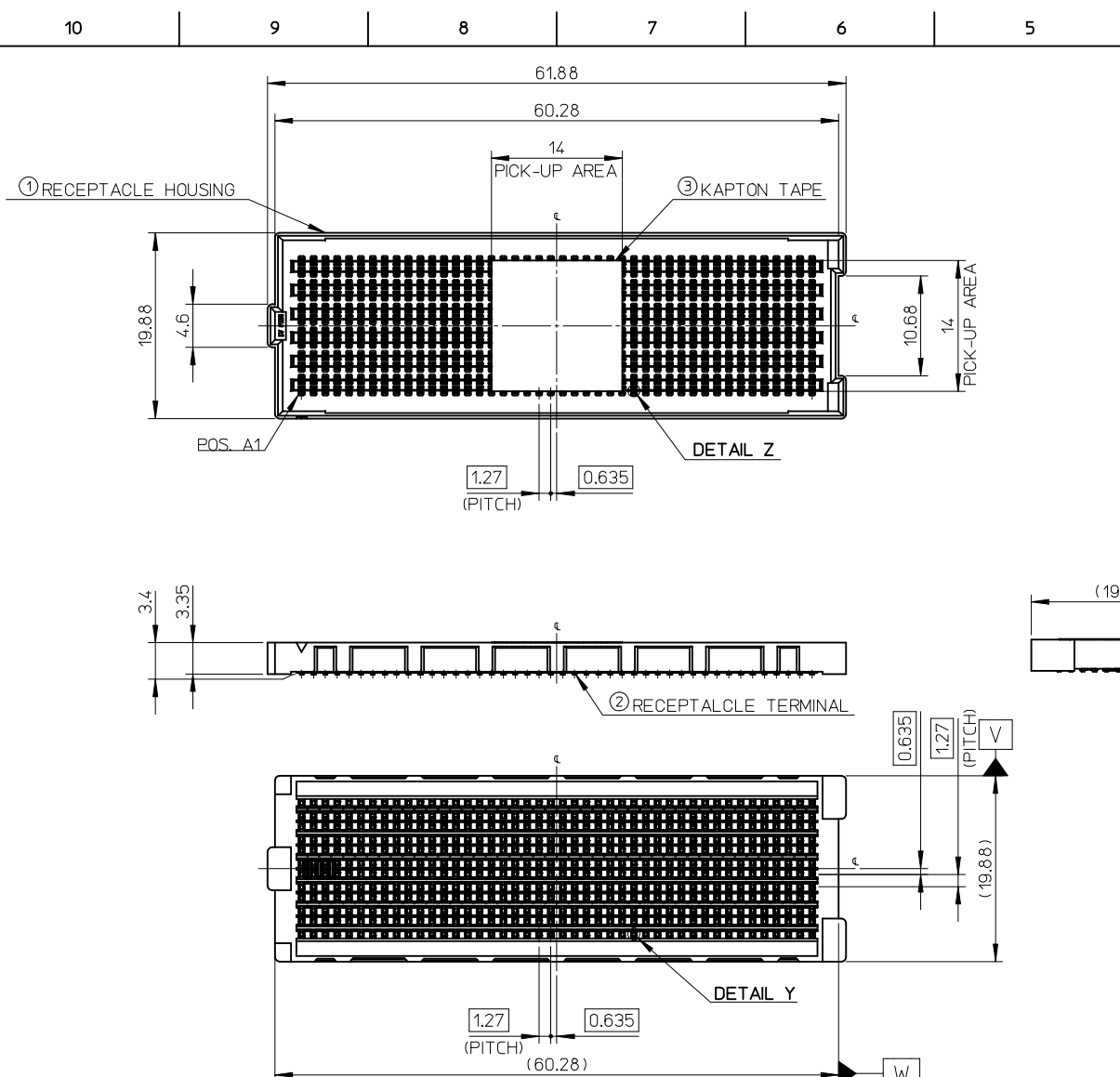
DETAIL "D"

RELEASED EC NO.: J2013-1305 DRW: MNISHIKAWA 2013/05/14 CHKD: KCHIKANO 2013/05/14 APPR: MYAGI 2013/05/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY MNISHIKAWA	DATE 2012/09/27	TITLE EMBOSSSED TAPE PKG FOR 1.27MMPITCH H=4.0 B-TO-B PLUG 528PIN	
	10 OVER 30 UNDER	±0.25	CHECKED BY KCHIKANO	DATE 2012/09/27		
	30 OVER	±0.3	APPROVED BY MYAGI	DATE 2012/10/02	<b>molex</b> DOCUMENT NO. SD-503821-003 SHEET NO. 1 OF 2	
ANGULAR ±1 °		MATERIAL NO. SEE CHART				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

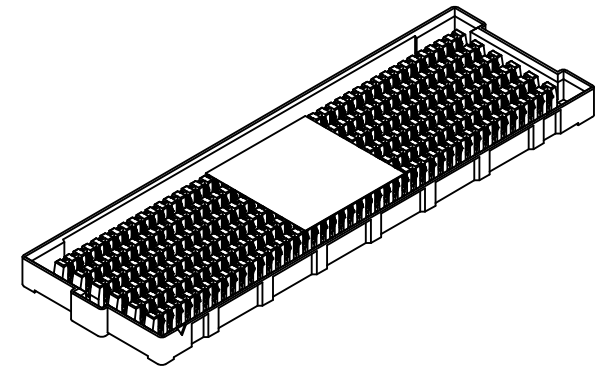


88	5038215281	528
キャリアテープ幅 CARRIER TAPE WIDTH	MATERIAL NO.	CKT.
	MODEL NO.	503821****

RELEASED EC NO. J2013-1305 DRWN: MNISHIKAWA 2013/05/14 CHKD: KCHIKANO 2013/05/14 APPR: MYAGI 2013/05/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY	1:1	METRIC	
	DESCRIPTION	10 UNDER	± 0.2	DRAWN BY	DATE	TITLE
		10 OVER 30 UNDER	± 0.25	MNISHIKAWA	2012/09/27	EMBOSSSED TAPE PKG FOR 1.27MMPITCH H=4.0 B-TO-B PLUG 528PIN
	30 OVER	± 0.3	KCHIKANO	2012/09/27		
	ANGULAR	± 1 °	MYAGI	2012/10/02		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.	SHEET NO.
			SEE CHART		SD-503821-003	2 OF 2
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



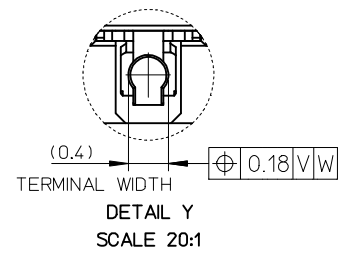
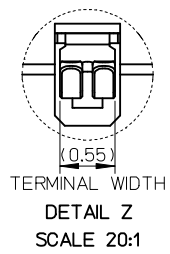
番号 No.	部品 PART	材質 MATERIAL
①	レセプタクル ハウジング RECEPTACLE HOUSING	液晶ポリマー、UL94V-0、黒色 LIQUID CRYSTAL POLYMER (LCP), UL94V-0, COLOR:BLACK
②	レセプタクル ターミナル RECEPTACLE TERMINAL	銅合金 COPPER ALLOY
③	カプトンテープ KAPTON TAPE	ポリイミド POLYIMIDE



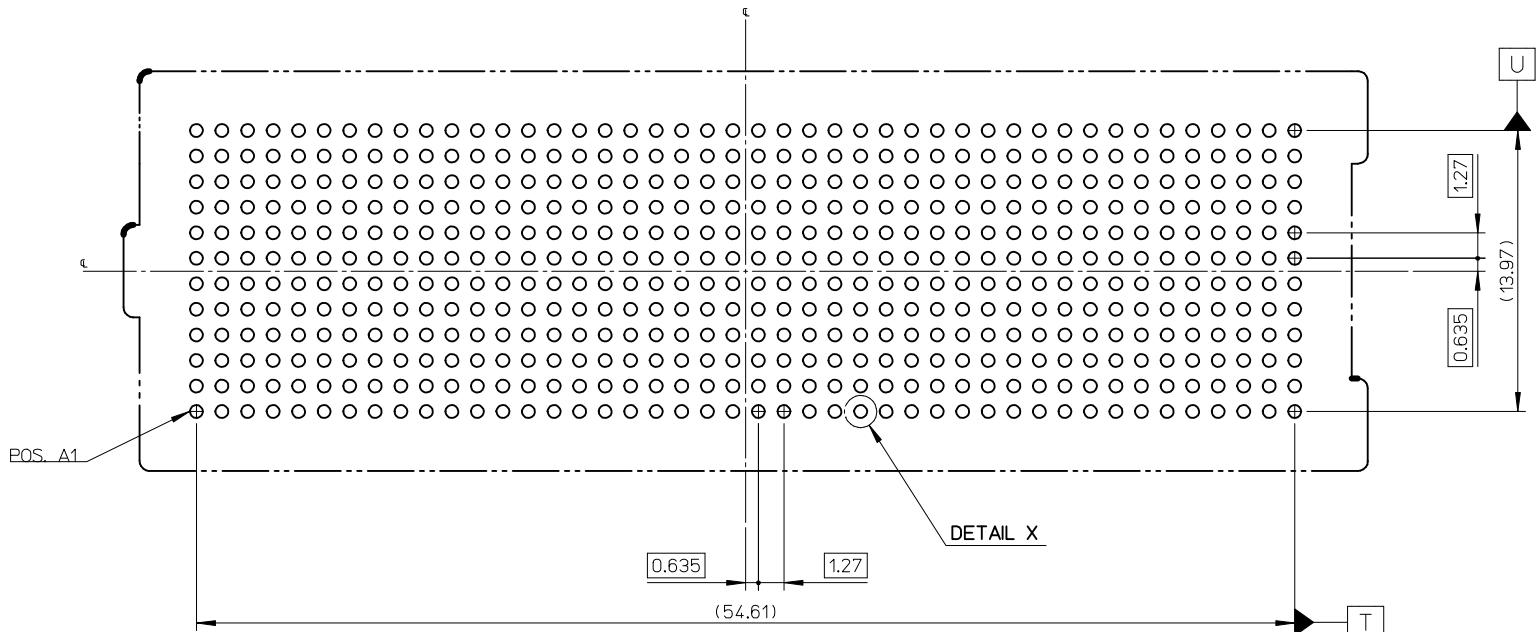
- NOTES
- メッキ仕様 PLATING  
金メッキ  
GOLD  
下地メッキ : ニッケルメッキ  
UNDER PLATING : NICKEL
  - 適合プラグ : 5038215281  
APPLICABLE PLUG : 5038215281
  - テール平坦度は0.15以下  
TAIL COPLANARITY TO BE 0.15 MAXIMUM.
  - ELV and RoHS COMPLIANT

5038255281	503825****
EMBOSSED PACKAGE	MODEL No.
ORDER No. オーダー番号	

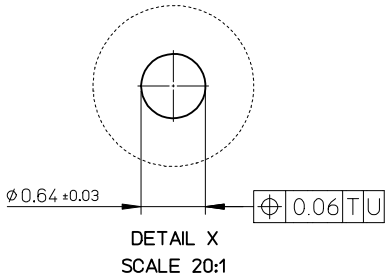
RELEASED EC NO. J2013-1305 DRW:MNISHIKAWA 2013/05/14 CHK:KCHIKANO 2013/05/14 APPR:MYAGI 2013/05/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY MNISHIKAWA	DATE 2012/10/01	TITLE <b>1.27MM PITCH B-TO-B CONN          HGT=4.0 528PIN          RECEPTACLE ASSEMBLY</b>  <b>molex</b> DOCUMENT NO. SD-503825-002 SHEET NO. 1 OF 2		
	10 OVER 30 UNDER	±0.25	CHECKED BY KCHIKANO	DATE 2012/10/01			
	30 OVER	±0.3	APPROVED BY MYAGI	DATE 2012/10/02			
ANGULAR ±1 °		MATERIAL NO. SEE TABLE					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



10 9 8 7 6 5 4 3 2 1



RECOMMENDED P.C.B.  
PATTERN LAYOUT



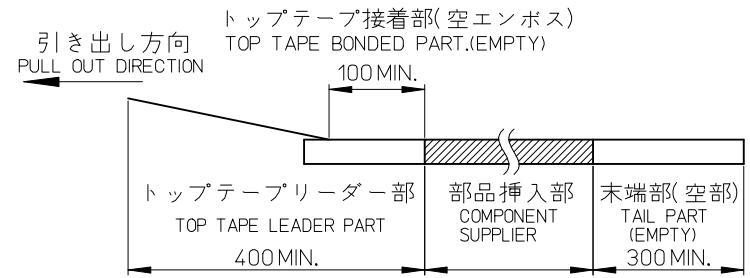
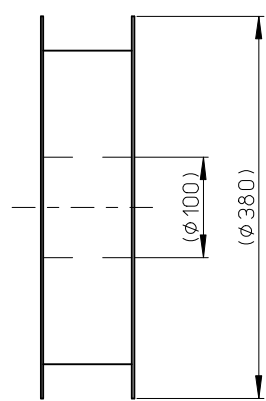
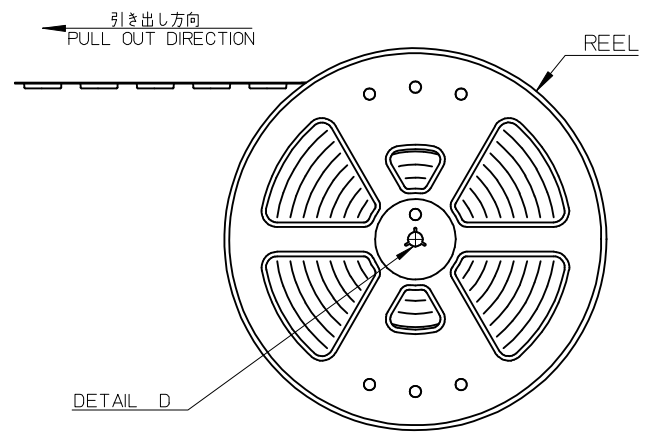
<b>RELEASED</b> EC NO: J2013-1305 DR/MN/ISHIKAWA 2013/05/14 CH/KD/KCHIKANO 2013/05/14 APPR:MYAGI 2013/05/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>		SCALE <b>4:1</b>	DESIGN UNITS <b>METRIC</b>	THIRD ANGLE PROJECTION	
	10 UNDER	$\pm 0.2$	DRAWN BY MNISHIKAWA	DATE 2012/10/01	TITLE <b>1.27MM PITCH B-TO-B CONN HGT=4.0 528PIN RECEPTACLE ASSEMBLY</b>			
	10 OVER 30 UNDER	$\pm 0.25$	CHECKED BY KCHIKANO	DATE 2012/10/01	<b>molex</b>			
	30 OVER	$\pm 0.3$	APPROVED BY MYAGI	DATE 2012/10/02	MATERIAL NO. <b>SEE SHEET 1</b>	DOCUMENT NO. <b>SD-503825-002</b>	SHEET NO. <b>2 OF 2</b>	
ANGULAR	$\pm 1^\circ$	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2

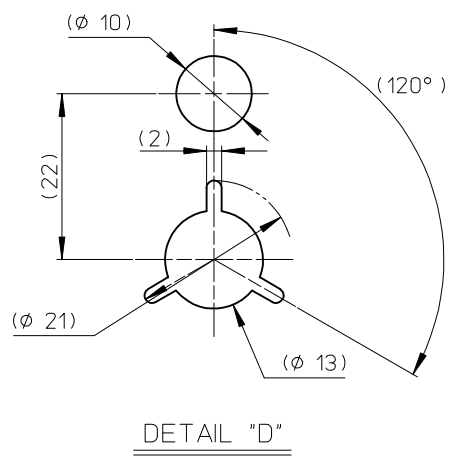


NOTES

- 製品詳細寸法については、SD 図面を参照下さい。  
THE DETAIL DIMENSION REFER TO SALES DRAWING.
- 梱包数量：500 個／リール  
NUMBER OF CONNECTORS : 500 PCS/REEL.
- リードテープ長さ LEAD TAPE LENGTH.

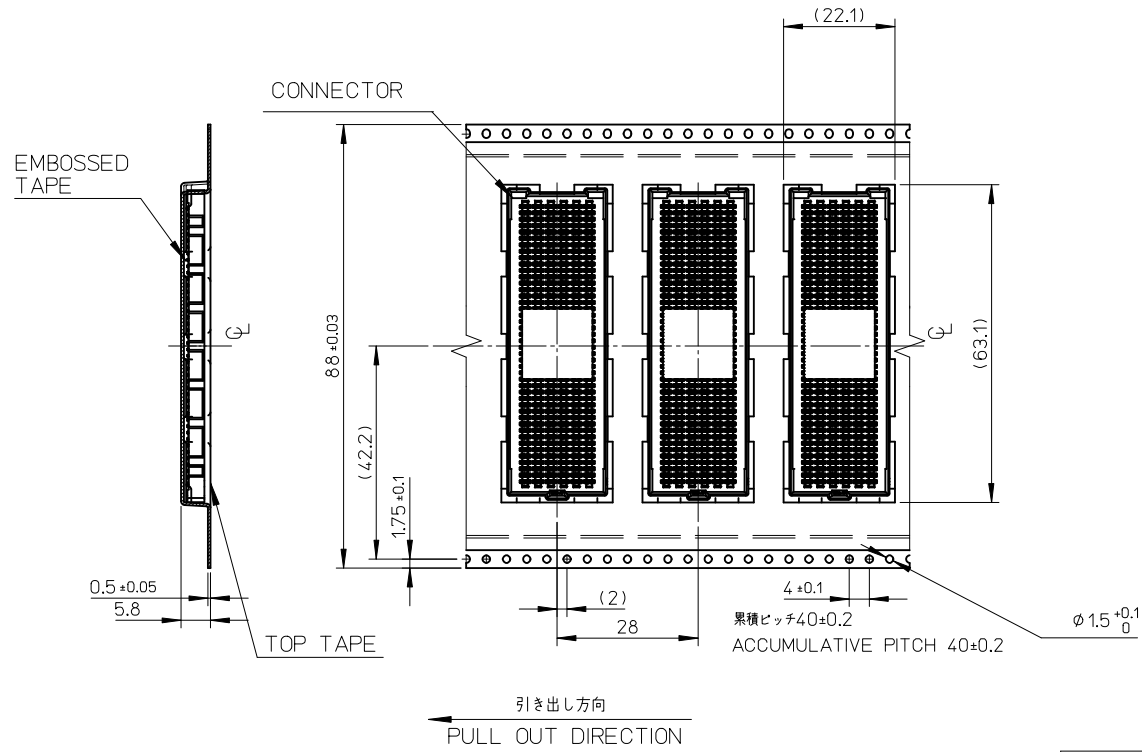


- トップテープの剥離強度については、IEC60286-3 に準拠  
TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.
- 材料 MATERIAL  
 キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)  
 トップテープ (TOP TAPE) : PET, OTHER  
 リール (REEL) : ポリスチレン (PS) <リサイクル材含む>  
 POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- ELV 及び RoHS 適合品  
ELV AND RoHS COMPLIANT



RELEASED EC NO.: J2013-1305 DRW: MNISHIKAWA 2013/05/14 CHKD: KCHIKANO 2013/05/14 APPR: MYAGI 2013/05/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY MNISHIKAWA	DATE 2012/09/27	TITLE EMBOSSED TAPE PKG FOR 1.27MMPITCH H=4.0 B-TO-B RECEPTACLE 528PIN	
	10 OVER 30 UNDER	±0.25	CHECKED BY KCHIKANO	DATE 2012/09/27		
	30 OVER	±0.3	APPROVED BY MYAGI	DATE 2012/10/02	<b>molex</b> DOCUMENT NO. SD-503825-003 SHEET NO. 1 OF 2	
ANGULAR ±1 °		MATERIAL NO. SEE CHART				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

10 9 8 7 6 5 4 3 2 1



88	5038255281	528
キャリアテープ幅 CARRIER TAPE WIDTH	MATERIAL NO.	CKT.
	MODEL NO.	503825****

<b>RELEASED</b> EC NO.: J2013-1305 DRWN: MNISHIKAWA 2013/05/14 CHKD: KCHIKANO 2013/05/14 APPR: MYAGI 2013/05/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
			MM ONLY	1:1	METRIC		
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE		
	10 OVER 30 UNDER	±0.25	MNISHIKAWA	2012/09/27	EMBOSSSED TAPE PKG FOR 1.27MMPITCH H=4.0 B-TO-B RECEPTACLE 528PIN		
	30 OVER	±0.3	CHECKED BY	DATE	<b>molex</b>		
ANGULAR ±1 °		KCHIKANO	2012/09/27				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
		MYAGI	2012/10/02	SEE CHART	SD-503825-003	2 OF 2	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2

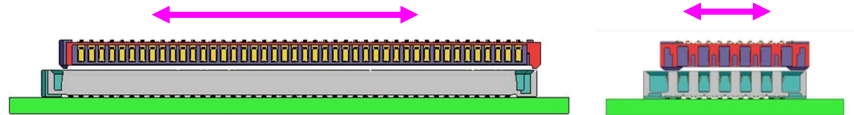
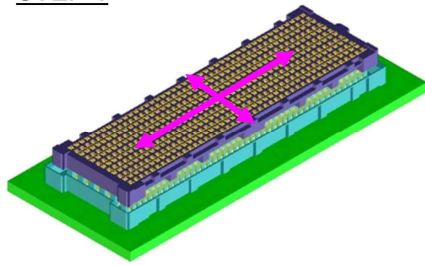


**【3. 嵌合に関して MATING】**

**3-1. 嵌合方法（挿入方法）HOW TO MATE (INSERTION)**

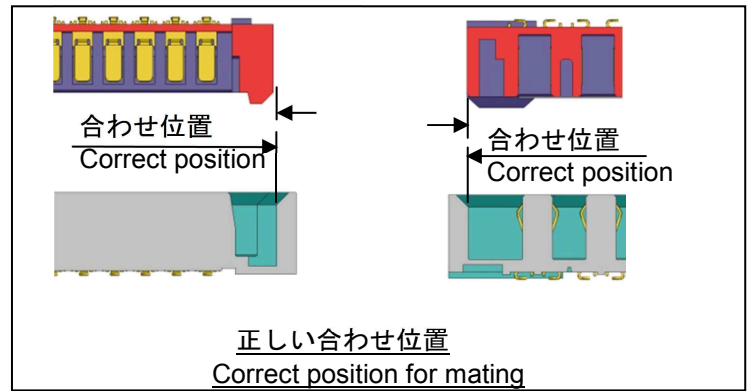
嵌合時（挿入時）は正しく位置合わせを行ってください。正しく位置合わせすると、基板間が約6.9mmになります。その後、プラグ側をリセ側と平行に保ったまま挿入して頂けます様、宜しくお願い致します。  
When connectors are positioned correctly for mating, the distance between PWB and FPC is about 6.9mm. After that, insert the plug to the receptacle in parallel with each other.

**STEP 1**

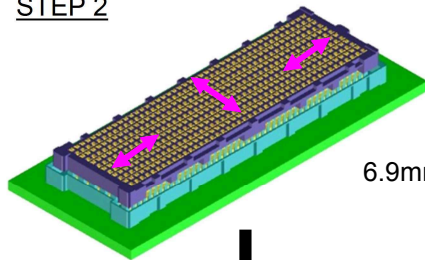


プラグ側をリセ側と平行にして位置合わせをしてください。  
Positioning the plug correctly in parallel with the receptacle

正しい位置合わせは右図の様に、リセ内壁とプラグ外壁で行ってください。  
Please find correct position at outside wall of receptacle and inside wall of plug.

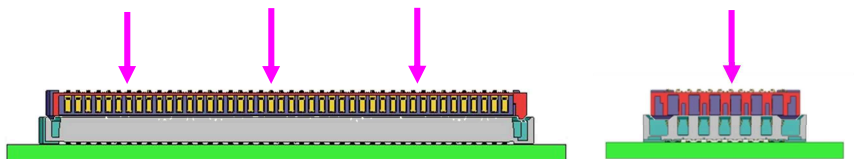
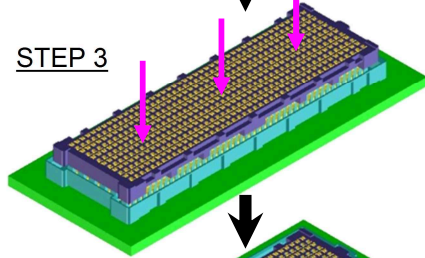


**STEP 2**



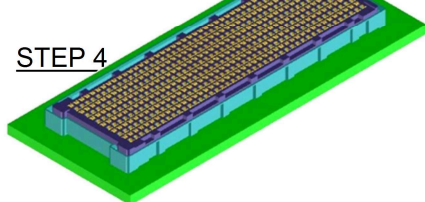
プラグ側を軽く動かし、位置合わせが正しいか確認してください。  
Position the plug correct by adjusting back or forth.

**STEP 3**



プラグ側をリセ側と平行に押し込んで下さい。  
Insert the plug in parallel with the receptacle until fully seated

**STEP 4**

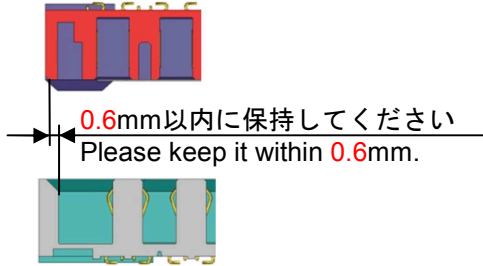


REVISE ON PC ONLY		TITLE: 1.27 BOARD TO BOARD CONNECTOR 528PIN (Hgt=4.0mm)	
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REV.	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

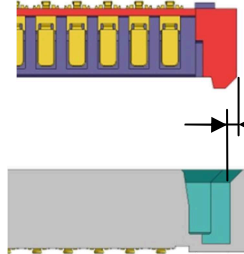
DOCUMENT NUMBER <b>AS-503825-001</b>	FILE NAME AS-503825-001.docx	SHEET 2 OF 8
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3-2. 嵌合時位置合わせ方法（平行な位置合わせが困難な場合） MATING POSITIONING WITH SLIGHTLY INCLINED

3-2-1. 長手方向に自由度がある場合 When operated in "a" Direction (lengthways)

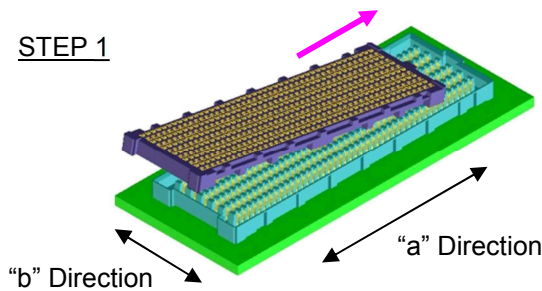


短手方向 "b" Direction

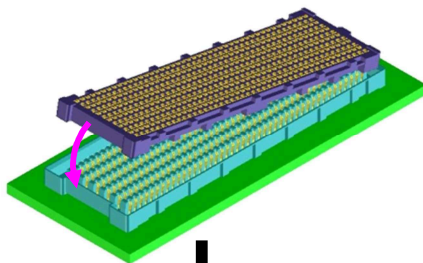


長手方向 "a" Direction (lengthways)

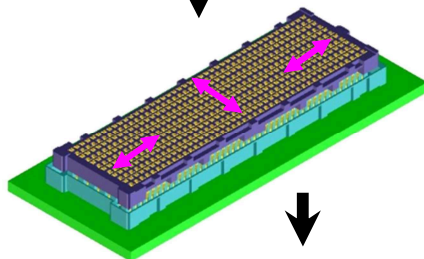
STEP 1



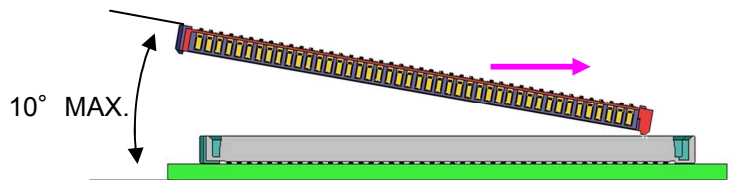
STEP 2



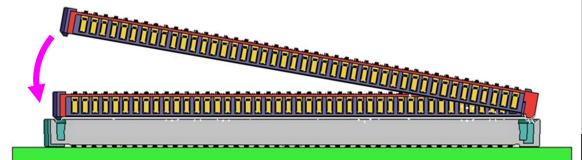
STEP 3



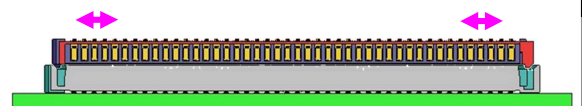
Please go to the STEP3 in sheet 2 of 8.



嵌合時の位置合わせは、プラグ側を少し傾けて（10°以下）行ってください。  
Position for mating by inclining the plug to the receptacle approximately less than 10° .



位置合わせを行った後、プラグ側とリセ側を平行にしてください。  
Once the plug is positioned over the receptacle, move it to the parallel position.



プラグ側を軽く動かし、位置合わせが正しいか確認してください。  
Position the plug correct by adjusting back or forth.

REVISE ON PC ONLY

**A**

SEE SHEET 1 OF 8

REV.

DESCRIPTION

TITLE: 1.27 BOARD TO BOARD CONNECTOR 528PIN  
(Hgt=4.0mm)

**CONFIDENTIAL アプリケーション仕様書**

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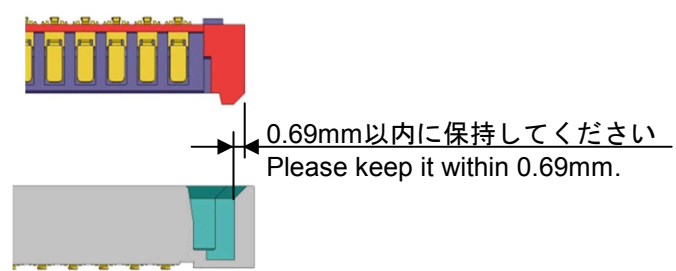
FILE NAME

AS-503825-001.docx

SHEET

3 OF 8

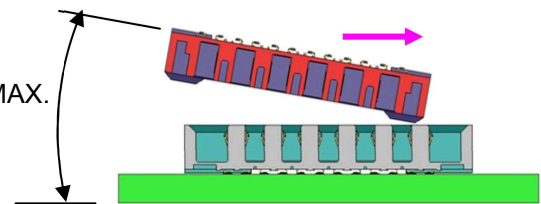
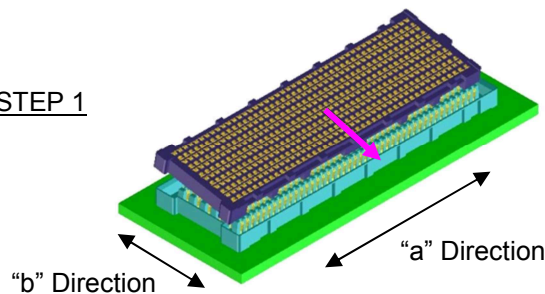
3-2-2. 短手方向に自由度がある場合 When operated in "b" Direction



短手方向 "b" Direction

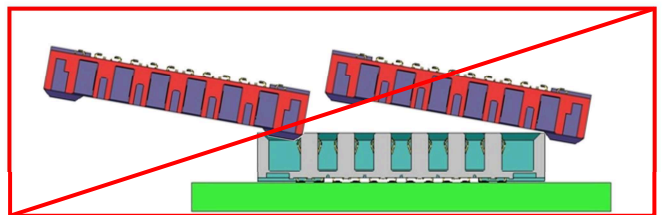
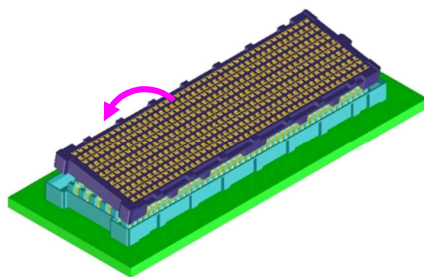
長手方向 "a" Direction (lengthways)

STEP 1



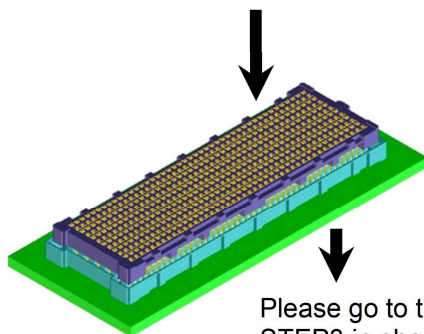
嵌合時の位置合わせは、プラグ側を少し傾けて (10° 以下) 行ってください。  
Position for mating by inclining the plug to the receptacle approximately less than 10°

STEP 2

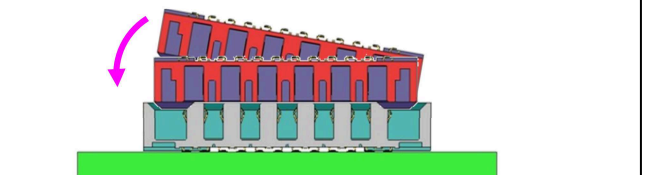


注) 位置合わせが大きくズレない様、ご注意ください。  
Notes) Please pay attention NOT to have the wrong position in "b" Direction.

STEP 3



Please go to the STEP3 in sheet 2.



位置合わせを行った後、プラグ側とリセ側を平行にしてください。  
Once the plug is positioned over the receptacle, move to the parallel position.

プラグ側を軽く動かし、位置合わせが正しいか確認してください。  
Position the plug correct by adjusting back or forth.

REVISE ON PC ONLY

A

SEE SHEET 1 OF 8

TITLE: 1.27 BOARD TO BOARD CONNECTOR 528PIN (Hgt=4.0mm)

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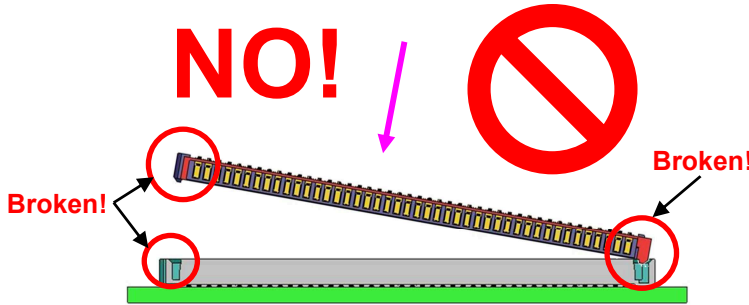
FILE NAME  
AS-503825-001.docx

SHEET  
4 OF 8

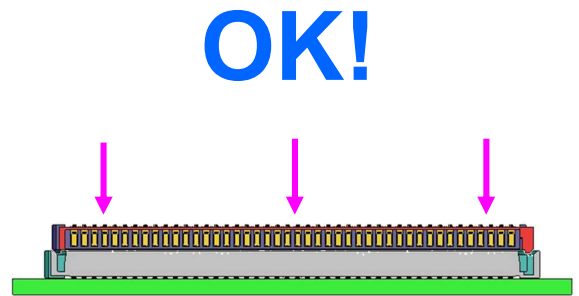
3-3. 嵌合時 取扱注意点 CONNECTOR HANDLING WHEN MATING

コネクタ同士は平行にして嵌合してください。コネクタ同士を平行に嵌合せず、斜めにしたまま嵌合すると、ハウジング同士が干渉し、ハウジングが破損する恐れがあります。

Please **DO NOT** apply force while mating the receptacle or plug at an angle in the “a” direction (lengthways). It may cause damage to the connector.



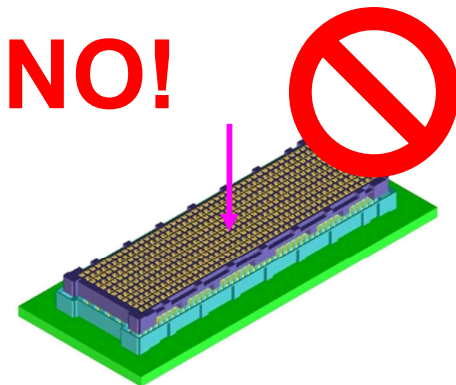
コネクタ斜め嵌合  
Mating with angle (Wrong Handling)



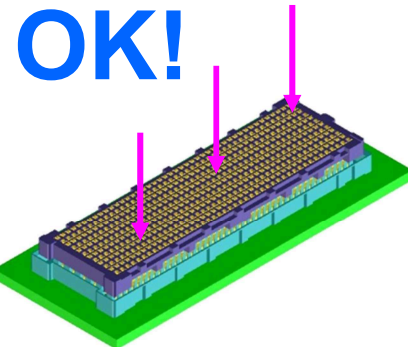
コネクタ平行嵌合  
Mating with Parallel (Correct Handling)

嵌合（挿入）の際は、コネクタ中央部のみの押し込みではなく、全体を平行に押し込んで頂けます様、お願い致します。

When mating (inserting), do NOT push the only center of the connector but the whole connector in parallel with the receptacle.



コネクタ中央部のみの押し込み  
Pushing Only Center (Wrong Handling)



コネクタ全体 平行押し込み  
Pushing Whole Paralleled (Correct Handling)

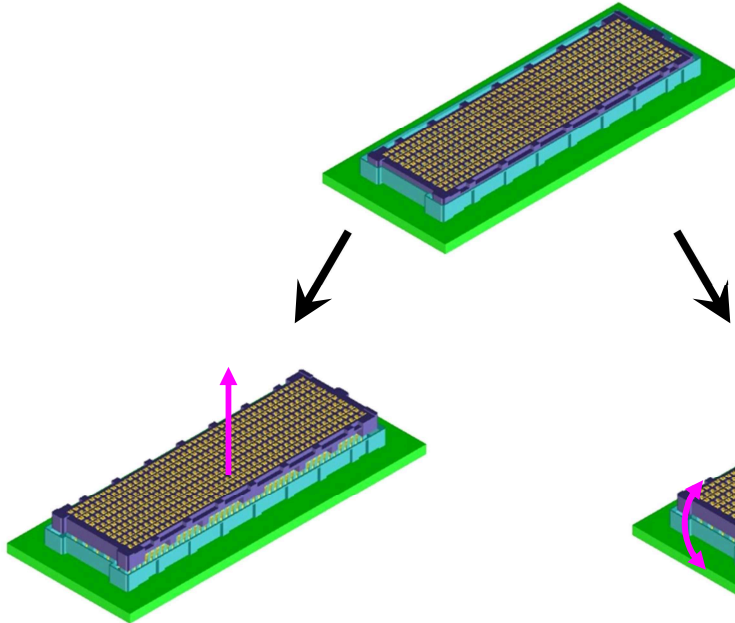
REVISE ON PC ONLY		TITLE: 1.27 BOARD TO BOARD CONNECTOR 528PIN (Hgt=4.0mm)	
<b>A</b>	SEE SHEET 1 OF 8	<b>CONFIDENTIAL</b>	<b>アプリケーション仕様書</b>
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DOCUMENT NUMBER <b>AS-503825-001</b>		FILE NAME AS-503825-001.docx	SHEET 5 OF 8
EN-037(2013-04 rev.1)			

【4. 抜去に関して UN-MATING】

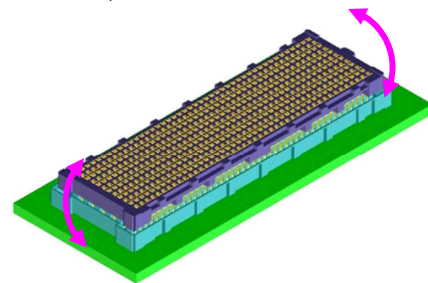
4-1. 抜去方法 HOW TO WITHDRAW

極力嵌合軸に沿って平行に抜去して頂くか、左右に少しずつ振りながら抜去して頂けます様、宜しくお願い致します。

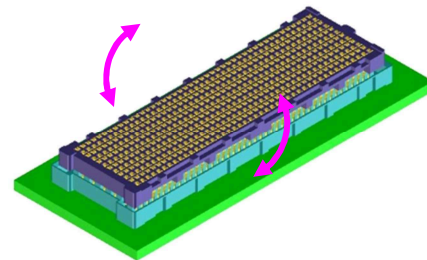
The plug should be released from the receptacle paralleled to the mated axis or by moving the plug slowly.



嵌合軸に沿って平行に抜く  
Releasing the plug paralleled to the mated axis



左右に少しずつ振りながら抜く（長手方向）  
Releasing the plug by moving slowly in "a" direction.  
(lengthways)



左右に少しずつ振りながら抜く（短手方向）  
Release the plug by moving slowly in "b" direction.

REVISE ON PC ONLY		TITLE: 1.27 BOARD TO BOARD CONNECTOR 528PIN (Hgt=4.0mm)	
<b>A</b>	SEE SHEET 1 OF 8	<b>CONFIDENTIAL</b>	<b>アプリケーション仕様書</b>
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DOCUMENT NUMBER <b>AS-503825-001</b>		FILE NAME AS-503825-001.docx	SHEET 6 OF 8
EN-037(2013-04 rev.1)			

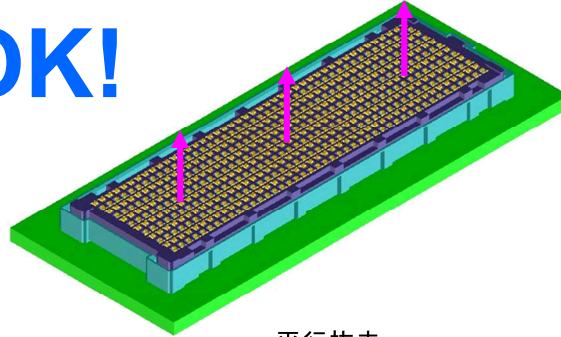


4-2. 抜去時 取扱注意点 CONNECTOR HANDLING WHEN WITHDRAWING

抜去の際に、過度のこじり抜去（斜め抜去）を行うとコネクタが破壊する可能性があります。

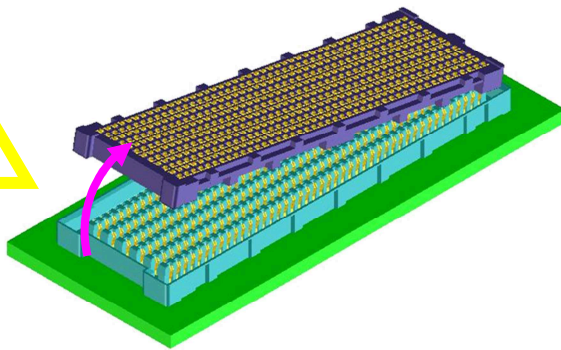
When un-mating (withdrawing), do NOT twist the plug to release. It may cause damage to the connector.

**OK!**



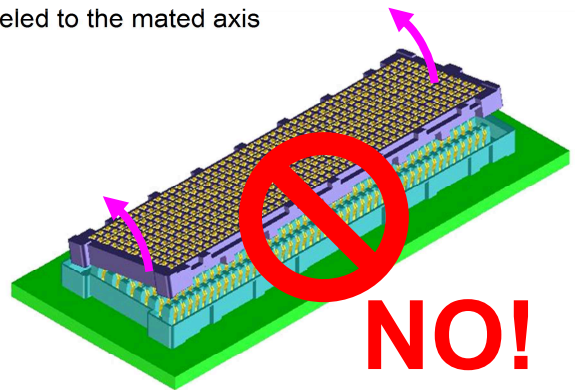
平行抜去

Releasing the plug paralleled to the mated axis



長手方向の斜め抜去

Slant releasing in "a" Direction (lengthways)



短手方向の斜め抜去

Slant releasing in "b" Direction

**NO!**

短手方向の斜め抜去は以下の理由からコネクタ破壊につながる可能性が高いため避けてください。

Please avoid slant releasing in "b" direction for the following reason.

- ・ 端子捲れが発生する可能性がある  
The receptacle terminals can be damaged
- ・ 端子が変形し不導通になる可能性がある  
The continuity defect can be caused by the damage to the terminals.

REVISE ON PC ONLY		TITLE: 1.27 BOARD TO BOARD CONNECTOR 528PIN (Hgt=4.0mm)	
<b>A</b>	SEE SHEET 1 OF 8	<b>CONFIDENTIAL</b>	<b>アプリケーション仕様書</b>
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EN-037(2013-04 rev.1)			

REV.	REV. RECORD	DATE	ECN NO.	WRITTEN BY :	CHECKED BY :
A	RELEASED	2013/05/14	J2013-1305	M.NISHIKAWA	K.CHIKANO

<b>A</b>	REVISE ON PC ONLY	TITLE: 1.27 BOARD TO BOARD CONNECTOR 528PIN (Hgt=4.0mm) <b>CONFIDENTIAL     アプリケーション仕様書</b>		
	SEE SHEET 1 OF 8			
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DOCUMENT NUMBER <b>AS-503825-001</b>		FILE NAME AS-503825-001.docx		SHEET 8 OF 8
EN-037(2013-04 rev.1)				



**【4. 性能 PERFORMANCESCOPE】**

**4-1. 電気的性能 Electrical Performance**

項目 Item		条件 Test Condition	規格 Requirement	
4-1-1	接触抵抗 Contact Resistance	コネクタを嵌合させ、開放電圧 20mV 以下、 短絡電流 10mA にて測定する。 (JIS C5402 5.4)  Mate connectors, measured by dry circuit, 20mV MAX., 10mA. (JIS C5402 5.4)	80 milliohm MAX.	
4-1-2	絶縁抵抗 Insulation Resistance	コネクタを嵌合させ、隣接するターミナル間及び ターミナル、アース間に、DC 250V を印加し測定する。 (JIS C5402 5.2/MIL-STD-202 試験法 302)  Mate connectors, apply 250V DC between adjacent terminal or ground. (JIS C5402 5.2/MIL-STD-202 Method 302)	100 Megohm MIN.	
4-1-3	耐電圧 Dielectric Strength	コネクタを嵌合させ、隣接するターミナル間及び ターミナル、アース間に、AC(rms) 250V (実効値) を 1分間 印加する。 (JIS C5402 5.1/MIL-STD-202 試験法 301)  Mate connectors, apply 250V AC(rms) for 1 minute between adjacent terminal or ground. (JIS C5402 5.1/MIL-STD-202 Method 301)	異状なきこと No Breakdown	
4-1-4	温度上昇 Temperature Rise	コネクタを嵌合させ、最大許容電流を 通電し、コネクタの温度上昇分を測定する。 (UL 498)  Connectors shall be mated and measure the temperature rise of contact, when the maximum AC Rated current is flowed. (UL 498)	温度上昇 Temperature Rise	30 °C maximum

REVISE ON PC ONLY

**B**

SEE SHEET 1 OF 10

TITLE:

1.27 BOARD TO BOARD CONNECTOR 528PIN  
(Hgt=4.0mm)

**PRODUCT SPECIFICATION**

**製品仕様書**

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DOCUMENT NUMBER  
**PS-503825-001**

FILE NAME

PS-503825-001.docx

SHEET

2 OF 10

## 4 - 2. 機械的性能 Mechanical Performance

項目 Item		条件 Test Condition	規格 Requirement
4-2-1	挿入力及び抜去力 Insertion and Withdrawal Force	毎分 25±3mm の速さで挿入、抜去を行う。 Insert and withdraw connectors at the speed rate of 25±3mm/minute.	第 6 項参照 Refer to paragraph 6
4-2-2	ターミナル保持力 Terminal / Housing Retention Force	ハウジングに装着されたターミナルを 毎分 25±3mm の速さで引張る。 Apply axial pull out force at the speed rate of 25±3mm/minute on the terminal pin assembled in the housing.	0.2N {0.020 kgf} minimum

## 4 - 3. 耐久性能 Durability Performances

項目 Item		条件 Test Condition	規格 Requirement	
4-3-1	繰返し挿抜 Repeated Insertion / Withdrawal	1分間 10回以下 の速さで挿入、 抜去を 50回 繰返す。 When mated up to 50 cycles repeatedly by the rate of 10 cycles per minute.	接触抵抗 Contact Resistance	100 milliohm MAX.
4-3-2	耐振動性 Vibration	DC 1mA 通電状態にて、嵌合軸を含む 互いに垂直な 3方向 に掃引割合 10~55~10 Hz/分、全振幅 1.5mm の振動 を 各2時間 加える。 (MIL-STD-202 試験法 201)  Amplitude : 1.5mm P-P Sweep time : 10~55~10 Hz in 1 minute Duration : 2 hours in each X.Y.Z. axes (MIL-STD-202 Method 201)	外観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	100 milliohm MAX.
			瞬断 Discontinuity	1.0 microsec. MAX.
4-3-3	耐衝撃性 Shock	DC 1mA 通電状態にて、嵌合軸を含む 互いに垂直な 6方向 に 490m/s <sup>2</sup> { 50G } の衝撃を 各3回 加える。 (JIS C60068-2-27/MIL-STD-202 試験法 213)  490m/s <sup>2</sup> { 50G }, 3 strokes in each X.Y.Z. axes. (JIS C60068-2-27/MIL-STD-202 Method 213)	外観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	100 milliohm MAX.
			瞬断 Discontinuity	1.0 microsec. MAX.

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**B**

SEE SHEET 1 OF 10

REV.

DESCRIPTION

TITLE:

 1.27 BOARD TO BOARD CONNECTOR 528PIN  
(Hgt=4.0mm)

**PRODUCT SPECIFICATION**
**製品仕様書**

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 DOCUMENT NUMBER  
**PS-503825-001**

FILE NAME

PS-503825-001.docx

SHEET

3 OF 10

項目 Item		条件 Test Condition	規格 Requirement	
4-3-4	耐熱性 Heat Resistance	コネクタを嵌合させ、85±2°C の雰囲気中に96時間 放置後取り出し、1~2時間 室温に放置する。 (JIS C60068-2-2/MIL-STD-202 試験法 108)  85±2°C, 96 hours (JIS C60068-2-2/MIL-STD-202 Method 108)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	100 milliohm MAX.
4-3-5	耐寒性 Cold Resistance	コネクタを嵌合させ、-55±3°C の雰囲気中に 96時間 放置後取り出し、1~2時間 室温に放置する。 (JIS C60068-2-1)  -55±3°C, 96 hours (JIS C60068-2-1)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	100 milliohm MAX.
4-3-6	耐湿性 Humidity	コネクタを嵌合させ、60±2°C、相対湿度 90~95% の雰囲気中に96時間 放置後取り出し、1~2時間 室温に放置する。 (JIS C60068-2-3/MIL-STD-202 試験法 103)  Temperature : 60±2°C Relative Humidity : 90~95% Duration : 96 hours (JIS C60068-2-3/MIL-STD-202 Method 103)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	100 milliohm MAX.
			耐電圧 Dielectric Strength	3-1-4項 満足のこと Must meet 4-1-3
			絶縁抵抗 Insulation Resistance	50 Megohm MIN.
4-3-7	温度サイクル Temperature Cycling	コネクタを嵌合させ、-55°C に 30分、+85°C に 30分 これを 1サイクル とし、5サイクル 繰返す。 但し、温度移行時間は 5分以内 とする。 試験後 1~2時間 室温に放置する。 (JIS C0025)  5 cycles of : a) -55°C 30 minutes b) +85°C 30 minutes (JIS C0025)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	100 milliohm MAX.

REVISE ON PC ONLY

**B**

SEE SHEET 1 OF 10

TITLE:

1.27 BOARD TO BOARD CONNECTOR 528PIN  
(Hgt=4.0mm)

**PRODUCT SPECIFICATION**

**製品仕様書**

THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO INC. AND MUST NOT BE USED WITHOUT WRITTEN PERMISSION

REV.

DESCRIPTION

DOCUMENT NUMBER  
**PS-503825-001**

FILE NAME

PS-503825-001.docx

SHEET

4 OF 10

項目 Item		条件 Test Condition	規格 Requirement	
4-3-8	塩水噴霧 Salt Spray	コネクタを嵌合させ、35±2°C にて 5±1% 重量比 の塩水を 48±4時間 噴霧し、試験後常温で水洗いした後、室温で乾燥させる。 (JIS C60068-2-11/MIL-STD-202 試験法 101)  48±4 hours exposure to a salt spray from the 5±1% solution at 35±2°C. (JIS C60068-2-11/MIL-STD-202 Method 101)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	100 milliohm MAX.
4-3-9	亜硫酸ガス SO <sub>2</sub> Gas	コネクタを嵌合させ、40±2°C にて 50±5ppm の亜硫酸ガス中に 24時間 放置する。  24 hours exposure to 50±5ppm. SO <sub>2</sub> gas at 40±2°C.	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	100 milliohm MAX.
4-3-10	半田付け性 Solderability	ターミナルまたはピンをフラックスに浸し、245±5°C の半田に 3±0.5秒 浸す。  Soldering Time : 3±0.5 sec. Solder Temperature : 245±5°C	濡れ性 Solder Wetting	浸漬した金めっき面積の 95% 以上 95% of immersed gold plating area must show no voids, no pin holes.
4-3-11	半田耐熱性 Resistance to Soldering Heat	第7項の条件にて、2回リフローを行う。 (When reflowing) Expose the specimen to infrared reflow condition the test item paragraph 7 two times	外観 Appearance	製品機能を損なう異常なきこと No Damage

( ) :参考規格 Reference Standard

{ } :参考単位 Reference Unit

**【5. 外観形状、寸法及び材質 PRODUCT SHAPE, DIMENSIONS AND MATERIALS】**

図面参照 Refer to the drawing.

ELV 及び RoHS適合品 ELV AND RoHS COMPLIANT.

REVISE ON PC ONLY		TITLE: 1.27 BOARD TO BOARD CONNECTOR 528PIN (Hgt=4.0mm)	
<b>B</b>	SEE SHEET 1 OF 10	<b>PRODUCT SPECIFICATION</b> <b>製品仕様書</b>	
	REV.	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO INC. AND MUST NOT BE USED WITHOUT WRITTEN PERMISSION
DOCUMENT NUMBER <b>PS-503825-001</b>		FILE NAME PS-503825-001.docx	SHEET 5 OF 10
EN-037(2013-04 rev.1)			

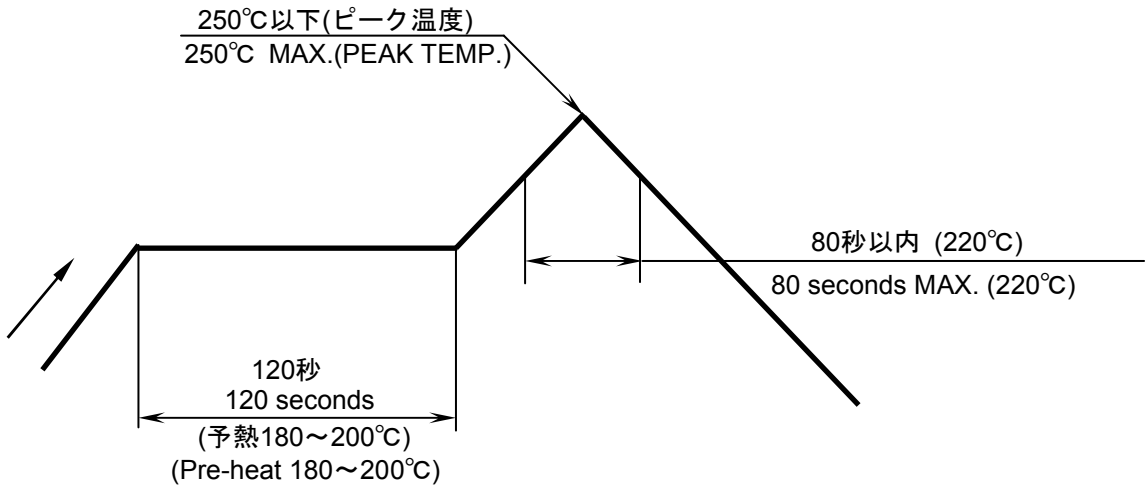
6. 挿入力及び抜去力 [INSERTION/WITHDRAWAL FORCE]

極数 No. of CKT	単位 UNIT	挿入力 (最大値) Insertion (MAX.)			抜去力 (最小値) Withdrawal (MIN.)		
		初回 1st	50回目 50th	100回目 100th	初回 1st	50回目 50th	100回目 100th
528	N	264	264	264	31.7	31.7	31.7

REVISE ON PC ONLY		TITLE: 1.27 BOARD TO BOARD CONNECTOR 528PIN (Hgt=4.0mm)	
<b>B</b>	SEE SHEET 1 OF 10	<b>PRODUCT SPECIFICATION</b> 製品仕様書	
REV.	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO INC. AND MUST NOT BE USED WITHOUT WRITTEN PERMISSION	
DOCUMENT NUMBER <b>PS-503825-001</b>		FILE NAME PS-503825-001.docx	SHEET 6 OF 10
EN-037(2013-04 rev.1)			



【7. 赤外線リフロー条件 INFRARED REFLOW CONDITION】



温度条件グラフ  
TEMPERATURE CONDITION GRAPH  
(基板表面温度)  
(TEMPERATURE ON BOARD PATTERN SIDE)

注記：本リフロー条件に関しては、リフロー装置及び基板などにより条件が異なりますので  
事前の実装評価（リフロー評価）の御確認を御願ひ致します。  
また窒素雰囲気で行う（N2リフロー）する場合にも、半田量や実装条件の  
ご確認をお願いいたします。

Please check the mount condition (reflow soldering condition) by your own devices beforehand,  
because the condition changes by the soldering devices, P.W. boards, and so on.

- ・推奨ランド寸法 Recommended Pattern dimension  
SDをご参照下さい。Refer to the Sales Drawing.
- ・推奨メタルマスク厚さ Recommended Thickness of metal mask  
t = 0.15 mm
- ・推奨メタルマスク開口率 Recommended Open aperture ratio of metal mask  
95~100% ( 大気リフロー時 for atmosphere )  
65~70% ( N2リフロー時 for Nitrogen atmosphere )

REVISE ON PC ONLY		TITLE: 1.27 BOARD TO BOARD CONNECTOR 528PIN (Hgt=4.0mm)	
<b>B</b>	SEE SHEET 1 OF 10	<b>PRODUCT SPECIFICATION</b> <b>製品仕様書</b>	
REV.	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO INC. AND MUST NOT BE USED WITHOUT WRITTEN PERMISSION	
DOCUMENT NUMBER <b>PS-503825-001</b>		FILE NAME PS-503825-001.docx	SHEET 7 OF 10
EN-037(2013-04 rev.1)			

【8. 取り扱い上の注意事項 INSTRUCTION UPON USAGE】

[嵌合]

嵌合は極力嵌合軸に沿って平行に行ってください。  
 その際、リセハウジングとプラグの外壁同士を合せる様に位置決めした後に押し込み嵌合して下さい。  
 斜めの嵌合になる場合は10°以下の角度でリセハウジングとプラグの外壁同士を軽く当て、位置決めした後に嵌合して下さい。

尚、コネクタ同士を過度に傾けた状態で嵌合を行いますと、ハウジングが破壊する恐れがありますのでこのような嵌合は避けて下さい。

Please mate the connector with parallel manner.

Please locate the inside wall of rec. housing and plug before mating.

In the case of skew mating, please do not mate the connector at more than 10° lead in angle .

Please do not mate connector at an angle as this manner, because the housing might be broken.

[抜去]

抜去は極力嵌合軸に沿って平行に行ってください。  
 または、左右に少しずつ振りながら行って下さい。  
 (過度のこじり抜去には注意して下さい。)

Please extract the connector with parallel manner.

or swing them right to left slightly.

(Please take care of excess twist extraction.)

【9. その他 注意事項 OTHERS】

- 嵌合の際、嵌合が不十分にならないようにご注意下さい。またセットへの組み込み後も、振動、衝撃等で嵌合の浮きが発生しないような状態にて使用してください。嵌合が浮き、基板同士あるいは基板とFPCが5度以上傾くと嵌合が抜ける可能性があります。  
 After mating, complete mating shall be confirmed. Please consider to take measure to hold the mated connectors with chassis against shock or vibration.  
 There may be case of coming off if mating is insufficient and connectors get a inclines of 5° .
- 端子に触らないでください  
 Please avoid touching terminals.
- 本製品の樹脂部にウエルド部の線、多少の傷が確認される事がありますが製品性能には影響ございません。  
 Although this product may have a weld line or a scratch on the housing, these will not have any influence on the product's performance.
- 一枚の基板にコネクタを複数実装する場合は、嵌合相手側はそれぞれ個別の基板に実装してご使用を願います。  
 There should not be more than one Board to board connection between two separate PCB boards. When mounting several board to board connectors between parallel printed circuit boards, please ensure to separate each mated board to board connector by using separate printed circuit boards.

REVISE ON PC ONLY		TITLE: 1.27 BOARD TO BOARD CONNECTOR 528PIN (Hgt=4.0mm)	
<b>B</b>	SEE SHEET 1 OF 10	<b>PRODUCT SPECIFICATION</b>	<b>製品仕様書</b>
REV.	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO INC. AND MUST NOT BE USED WITHOUT WRITTEN PERMISSION	
DOCUMENT NUMBER <b>PS-503825-001</b>		FILE NAME PS-503825-001.docx	SHEET 8 OF 10
EN-037(2013-04 rev.1)			

5. 実装時は位置決めマーク（フィデューシャルマーク）等を設け、実装ずれに注意してください。  
There are instructions of design the following. Please prepared without pattern area.
6. 本製品の一般性能確認はガラスエポキシ基板にて実施しております。フレキシブル基板等の特殊な基板へ実装する場合は、事前に実装確認等を行った上で使用願います。  
This connector performance was tested based on using rigid epoxy-glass printed circuit board. If you need to reflow the connector on the flexible circuit board, please make sure to conduct the reflow test in advance.
7. フレキシブル基板に実装する場合は、基板の変形を防止するため補強板のご使用をお勧めします。  
Please add a stiffener on the flexible printed circuit (FPC) when you mount the connector onto FPC in order to prevent deformation of the FPC.
8. 本製品は低背のため、接点部への半田上がりが発生しないように、リフロー条件を設定して下さい。  
Due to the low profile design, please be cautious to set the reflow condition to prevent solder wicking.
9. 実装条件（基板、メタルマスク、クリーム半田など）により、コネクタの実装状態（半田上がり）が異なることがあります。  
Fillet condition might be different depending on the mounting condition, please care of fillet condition of connectors.
10. リフロー条件によっては樹脂部の変色や端子めっき部にヨリが発生する場合がありますが、製品性能に影響はございません。  
Depending on the reflow conditions, there may be the possibility of a color change in the housing or the plating surface looks wavy. However, these are not any effect on the product's performance.
11. リフロー後、半田付け部に变色が見られることがありますが、製品性能に影響はありません。  
また、製品仕様上、テール上面まで半田濡れ上がりはありませんが、製品性能上問題ありません。  
There is no influence in the product performance though discoloration might be seen in the soldering tail after the reflow. There are no solders on the top surface of tail in spec, and there is no influence in performance.
12. 実装後において手半田コテによるリペアーを行なう際は、必ず仕様書掲載の条件以内で行なって下さい。  
条件を超えて実施した場合、端子の抜け、接点ギャップの変化、モールドの変形、熔融等、破損の原因になります。  
When you need to repair the connector after reflow by using a solder iron, please perform under the conditions of this product specification (3-3-11).
13. 基板実装後に基板を直接積み重ねないように注意してください。  
Please do not stack the printed circuit board directly after mounted the connector on it.
14. 本製品をSn-Ag-Cu系(重量比96.5%-3%-0.5%)以外の半田でご使用される場合は、事前に半田付け性、半田剥離強度などをご確認くださいようお願いいたします。  
If an alternative solder past is used (other than Sn-Ag-Cu 96.5%-3%-0.5%), please ensure in advance that the solderability and PWB peeling force will not have any issues.

REVISE ON PC ONLY		TITLE:	
<b>B</b>	SEE SHEET 1 OF 10	1.27 BOARD TO BOARD CONNECTOR 528PIN (Hgt=4.0mm)	
		<b>PRODUCT SPECIFICATION</b> <b>製品仕様書</b>	
REV.	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO INC. AND MUST NOT BE USED WITHOUT WRITTEN PERMISSION	
DOCUMENT NUMBER <b>PS-503825-001</b>		FILE NAME PS-503825-001.docx	SHEET 9 OF 10
EN-037(2013-04 rev.1)			

# molex PRODUCT SPECIFICATION

LANGUAGE

JAPANESE  
ENGLISH

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A	RELEASED	2013/05/14	J2013-1305	M.NISHIKAWA	K.CHIKANO
B	REVISED	2013/06/05	J2013-1461	M.NISHIKAWA	K.CHIKANO

<b>B</b>	REVISE ON PC ONLY	TITLE: 1.27 BOARD TO BOARD CONNECTOR 528PIN (Hgt=4.0mm) <b>PRODUCT SPECIFICATION</b> <b>製品仕様書</b>	
	SEE SHEET 1 OF 10		
	REV.	DESCRIPTION	FILE NAME
DOCUMENT NUMBER <b>PS-503825-001</b>		PS-503825-001.docx	10 OF 10
EN-037(2013-04 rev.1)			